

NCE N-Channel Enhancement Mode Power MOSFET

Description

The NCE60H18 uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. This device is suitable for use in PWM, load switching and general purpose applications.

General Features

● V_{DS} =60V, I_{D} =180A $R_{DS(ON)}$ < 3mΩ @ V_{GS} =10V (Typ:2.5mΩ)

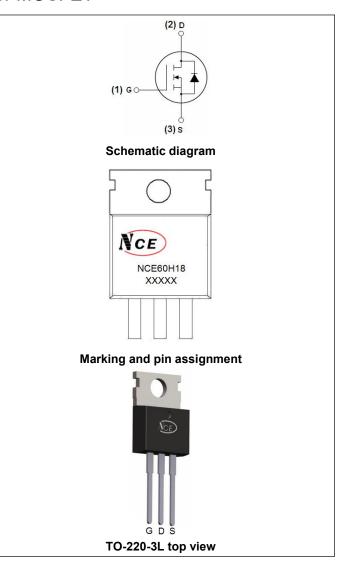
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Special designed for convertors and power controls
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

Application

- Power switching application
- Hard switched and High frequency circuits
- Uninterruptible power supply

100% UIS TESTED!

100% ΔVds TESTED!



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE60H18	NCE60H18	TO-220-3L	-	-	-

Absolute Maximum Ratings (T_A=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	60	V
Gate-Source Voltage	V _G S	±20	V
Drain Current-Continuous	I _D	180	А
Drain Current-Continuous(T _C =100 °C)	I _D (100°C)	126	А
Pulsed Drain Current	I _{DM}	540	А
Maximum Power Dissipation	P _D	200	W
Derating factor		1.33	W/℃
Single pulse avalanche energy (Note 5)	Eas	1730	mJ
Operating Junction and Storage Temperature Range	T _J ,T _{STG}	-55 To 175	$^{\circ}$ C



Thermal Characteristic

Thermal Resistance,Junction-to-Case ^(Note 2)	R _{θJC}	0.75	°C/W	
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Electrical Characteristics (T_A=25°Cunless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	'		,			
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250µA	60	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	Igss	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)	'		•			
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250µA	2	3	4	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =20A	-	2.5	3	mΩ
Forward Transconductance	g FS	V _{DS} =20V,I _D =20A	-	60	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{lss}	V _{DS} =30V,V _{GS} =0V, F=1.0MHz	-	9840	-	PF
Output Capacitance	Coss		-	820	-	PF
Reverse Transfer Capacitance	C _{rss}		-	662	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		-	40	-	nS
Turn-on Rise Time	t _r	VDD=30V,RL=1.5Ω	-	25	-	nS
Turn-Off Delay Time	t _{d(off)}	VDD=30V,RL=1.5Ω RG=2.5Ω,VGS=10V	-	110	-	nS
Turn-Off Fall Time	t _f		-	30	-	nS
Total Gate Charge	Qg	N/ 00\/ L 00A	-	200	-	nC
Gate-Source Charge	Q _{gs}	F=1.0MHz VDD=30V,RL=1.5Ω	-	46	-	nC
Gate-Drain Charge	Q _{gd}	V _{GS} =10V	-	60	-	nC
Drain-Source Diode Characteristics	'		,			
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =20A	-	-	1.2	V
Diode Forward Current (Note 2)	Is		-	-	180	Α
Reverse Recovery Time	t _{rr}	Tj=25℃,I _F =100A	-		60	nS
Reverse Recovery Charge	Qrr	di/dt=100A/µs (Note3)	-		110	nC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negl	ligible (turi	n-on is do	ominated b	y LS+LD)

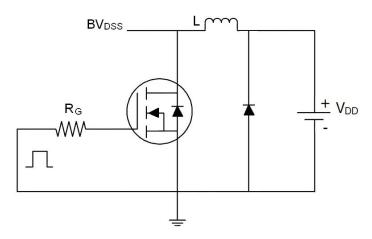
Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production
- **5.** EAS condition: Tj=25 $^{\circ}$ C,VDD=30V,VG=10V,L=0.5mH,Rg=25 Ω

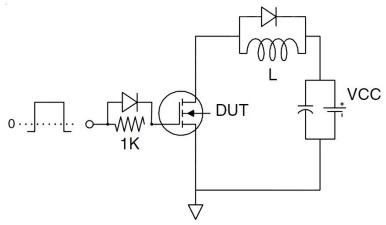


Test Circuit

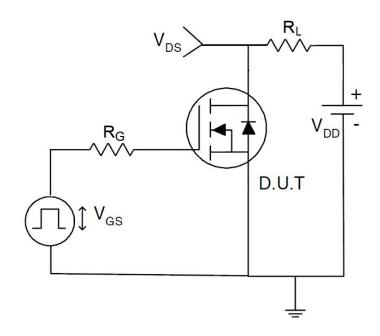
1) E_{AS} Test Circuits



2) Gate Charge Test Circuit



3) Switch Time Test Circuit





Typical Electrical and Thermal Characteristics (Curves)

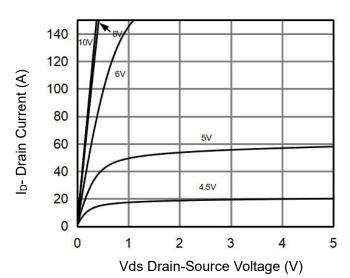


Figure 1 Output Characteristics

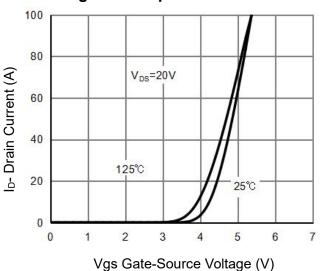


Figure 2 Transfer Characteristics

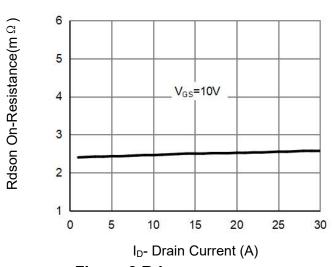


Figure 3 Rdson- Drain Current

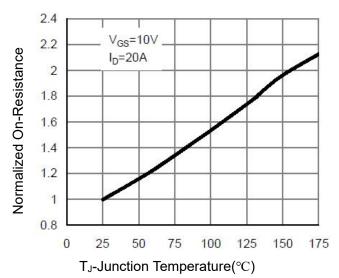


Figure 4 Rdson-Junction Temperature

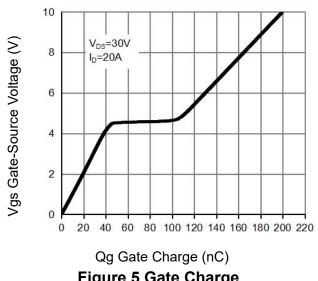


Figure 5 Gate Charge

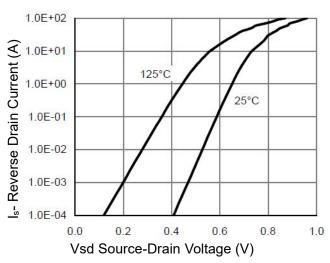


Figure 6 Source- Drain Diode Forward





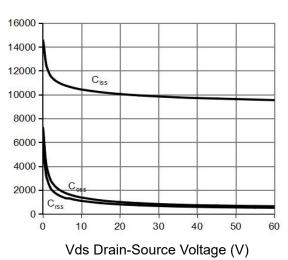


Figure 7 Capacitance vs Vds

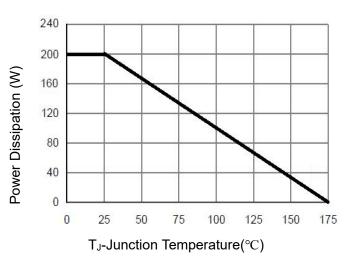
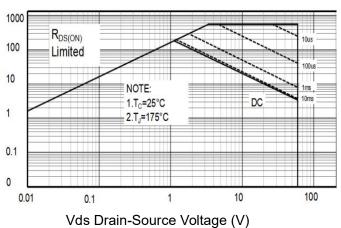
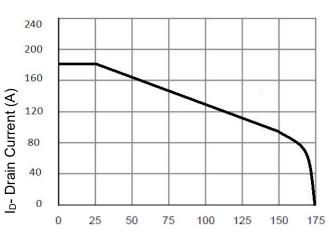


Figure 9 Power De-rating





T_J-Junction Temperature(°C) Figure 10 I_D Current De-rating



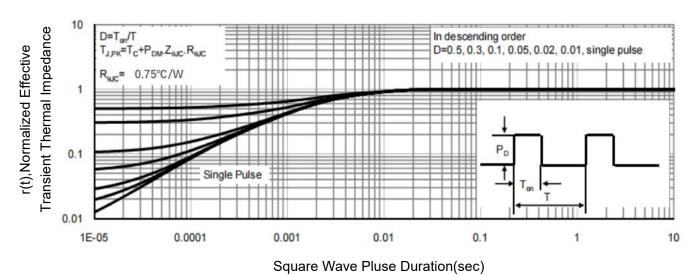
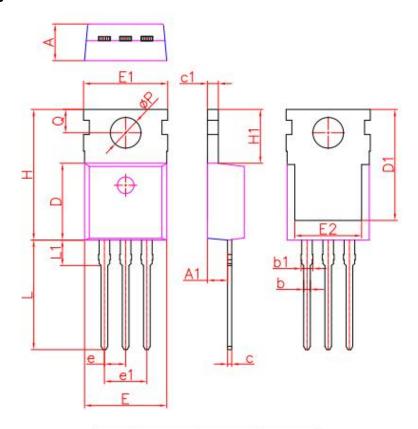


Figure 11 Normalized Maximum Transient Thermal Impedance



TO-220-3L Package Information



DIM.	MIN.	NOM.	MAX.		
Α	4.20	4.40	4.60		
A1	2.25	2.40	2.55		
ь	0.70	0.80	0.90		
b1	1.17	1.27	1.37		
С	0.33	0.50	0.65		
c1	1.20	1.30	1.40		
D	8.95	9.20	9.75		
D1	13.10	13.30	13.50		
Ε	9.74	9.84	10.04		
E1	9.91	10.08	10.25		
E2	7.90	8.00	8.10		
е	2.54BSC				
e1		5.08BSC			
Н	15.45	15.65	15.85		
H1	6.30	6.45	6.60		
L	12.90	13.13	13.40		
L1	2.85	3.05	3.25		
Q	2.65	2.80	2.95		
ØΡ	3.40	3.68	3.80		



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